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What are **Embedded - System On Chip (SoC)?** 

**System On Chip (SoC)** integrates multiple functions of a computer or electronic system onto a single chip. Unlike traditional multi-chip solutions. SoCs combine a central

Details	
Product Status	Active
Architecture	MCU, FPGA
Core Processor	Dual ARM® Cortex®-A9 MPCore™ with CoreSight™
Flash Size	-
RAM Size	64KB
Peripherals	DMA, POR, WDT
Connectivity	CANbus, EBI/EMI, Ethernet, I <sup>2</sup> C, MMC/SD/SDIO, SPI, UART/USART, USB OTG
Speed	800MHz
Primary Attributes	FPGA - 25K Logic Elements
Operating Temperature	-40°C ~ 100°C (TJ)
Package / Case	672-FBGA
Supplier Device Package	672-UBGA (23x23)
Purchase URL	https://www.e-xfl.com/product-detail/intel/5csxfc2c6u23i7n

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# **Cyclone V Device Overview**

The Cyclone® V devices are designed to simultaneously accommodate the shrinking power consumption, cost, and time-to-market requirements; and the increasing bandwidth requirements for high-volume and cost-sensitive applications.

Enhanced with integrated transceivers and hard memory controllers, the Cyclone V devices are suitable for applications in the industrial, wireless and wireline, military, and automotive markets.

### **Related Information**

Cyclone V Device Handbook: Known Issues

Lists the planned updates to the Cyclone V Device Handbook chapters.

## **Key Advantages of Cyclone V Devices**

Table 1. Key Advantages of the Cyclone V Device Family

Advantage	Supporting Feature
Lower power consumption	Built on TSMC's 28 nm low-power (28LP) process technology and includes an abundance of hard intellectual property (IP) blocks     Up to 40% lower power consumption than the previous generation device
Improved logic integration and differentiation capabilities	8-input adaptive logic module (ALM)     Up to 13.59 megabits (Mb) of embedded memory     Variable-precision digital signal processing (DSP) blocks
Increased bandwidth capacity	3.125 gigabits per second (Gbps) and 6.144 Gbps transceivers     Hard memory controllers
Hard processor system (HPS) with integrated Arm* Cortex*-A9 MPCore* processor	<ul> <li>Tight integration of a dual-core Arm Cortex-A9 MPCore processor, hard IP, and an FPGA in a single Cyclone V system-on-a-chip (SoC)</li> <li>Supports over 128 Gbps peak bandwidth with integrated data coherency between the processor and the FPGA fabric</li> </ul>
Lowest system cost	Requires only two core voltages to operate  Available in low-cost wirebond packaging  Includes innovative features such as Configuration via Protocol (CvP) and partial reconfiguration



# **Summary of Cyclone V Features**

**Summary of Features for Cyclone V Devices** Table 2.

Feature		Description					
Technology	TSMC's 28-nm low-p 1.1 V core voltage	ower (28LP) process technology					
Packaging	Multiple device densi different device densi	Multiple device densities with compatible package footprints for seamless migration between different device densities					
High-performance FPGA fabric	Enhanced 8-input ALM v	vith four registers					
Internal memory blocks	•	(b) memory blocks with soft error correction code (ECC) block (MLAB)—640-bit distributed LUTRAM where you can use up to 25% memory					
Embedded Hard IP blocks	<ul> <li>Variable-precision DSP</li> <li>Native support for up to three signal processing precision leve (three 9 x 9, two 18 x 18, or one 27 x 27 multiplier) in the sa variable-precision DSP block</li> <li>64-bit accumulator and cascade</li> <li>Embedded internal coefficient memory</li> <li>Preadder/subtractor for improved efficiency</li> </ul>						
	Memory controller	DDR3, DDR2, and LPDDR2 with 16 and 32 bit ECC support					
	Embedded transceiver I/O	PCI Express* (PCIe*) Gen2 and Gen1 (x1, x2, or x4) hard IP with multifunction support, endpoint, and root port					
Clock networks		ol clock network d peripheral clock networks are not used can be powered down to reduce dynamic power					
Phase-locked loops (PLLs)	<ul><li>Precision clock synth</li><li>Integer mode and from</li></ul>	esis, clock delay compensation, and zero delay buffering (ZDB) actional mode					
FPGA General-purpose I/Os (GPIOs)	400 MHz/800 Mbps 6     On-chip termination	cond (Mbps) LVDS receiver and 840 Mbps LVDS transmitter external memory interface (OCT) p to 16 mA drive strength					
Low-power high-speed serial interface	Transmit pre-emphase	Sbps integrated transceiver speed sis and receiver equalization infiguration of individual channels					
HPS (Cyclone V SE, SX, and ST devices only)	<ul> <li>Single or dual-core Arm Cortex-A9 MPCore processor-up to 925 MHz maximum frequency with support for symmetric and asymmetric multiprocessing</li> <li>Interface peripherals—10/100/1000 Ethernet media access control (EMAC), USB 2.0 On-The-GO (OTG) controller, quad serial peripheral interface (QSPI) flash controller, NAND flash controller, Secure Digital/MultiMediaCard (SD/MMC) controller, UART, controller area network (CAN), serial peripheral interface (SPI), I<sup>2</sup>C interface, and up to 85 HPS GPIO interfaces</li> </ul>						
		-general-purpose timers, watchdog timers, direct memory access (DMA) iguration manager, and clock and reset managers ot ROM					
	·	continued					

<sup>(1)</sup> Contact Intel for availability.



### **Related Information**

True LVDS Buffers in Devices, I/O Features in Cyclone V Devices
Provides the number of LVDS channels in each device package.

## **Package Plan**

**Table 5.** Package Plan for Cyclone V E Devices

Member Code	M383 (13 mm)	M484 (15 mm)	U324 (15 mm)	F256 (17 mm)	U484 (19 mm)	F484 (23 mm)	F672 (27 mm)	F896 (31 mm)
	GPIO							
A2	223	_	176	128	224	224	_	_
A4	223	_	176	128	224	224	_	_
A5	175	_	_	_	224	240	_	_
A7	_	240	_	_	240	240	336	480
A9	_	_	_	_	240	224	336	480

## **Cyclone V GX**

This section provides the available options, maximum resource counts, and package plan for the Cyclone V GX devices.

The information in this section is correct at the time of publication. For the latest information and to get more details, refer to the *Product Selector Guide*.

## **Related Information**

**Product Selector Guide** 

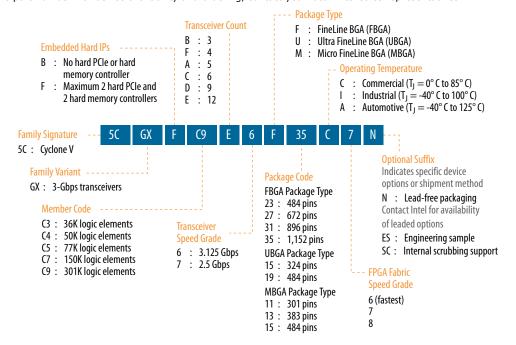
Provides the latest information about Intel products.



## **Available Options**

### Figure 2. Sample Ordering Code and Available Options for Cyclone V GX Devices

The SEU internal scrubbing feature is available for Cyclone V E, GX, SE, and SX devices with the "SC" suffix in the part number. For device availability and ordering, contact your local Intel sales representatives.



### **Maximum Resources**

**Table 6.** Maximum Resource Counts for Cyclone V GX Devices

Reso	urce	Member Code						
		С3	C4	<b>C5</b>	<b>C7</b>	С9		
Logic Elements (	(LE) (K)	36	50	77	150	301		
ALM		13,460	18,860	29,080	56,480	113,560		
Register	Register		75,440	116,320	225,920	454,240		
Memory (Kb)	M10K	1,350	2,500	4,460	6,860	12,200		
	MLAB	182	424	424	836	1,717		
Variable-precision	n DSP Block	57	70	150	156	342		
18 x 18 Multiplie	er	114	140	300	312	684		
PLL		4	6	6	7	8		
3 Gbps Transceiver		3	6	6	9	12		
GPIO <sup>(4)</sup>		208	336	336	480	560		
						continued		

<sup>(4)</sup> The number of GPIOs does not include transceiver I/Os. In the Intel Quartus® Prime software, the number of user I/Os includes transceiver I/Os.



## **Cyclone V SE**

This section provides the available options, maximum resource counts, and package plan for the Cyclone V SE devices.

The information in this section is correct at the time of publication. For the latest information and to get more details, refer to the *Product Selector Guide*.

#### **Related Information**

**Product Selector Guide** 

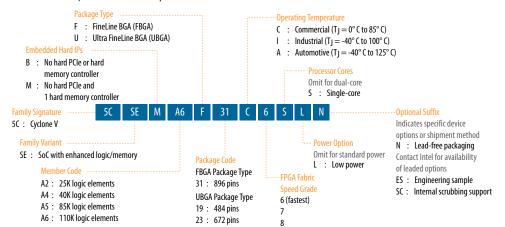
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### **Available Options**

### Figure 4. Sample Ordering Code and Available Options for Cyclone V SE Devices

The SEU internal scrubbing feature is available for Cyclone V E, GX, SE, and SX devices with the "SC" suffix in the part number. For device availability and ordering, contact your local Intel sales representatives.

Cyclone V SE and SX low-power devices (L power option) offer 30% static power reduction for devices with 25K LE and 40K LE, and 20% static power reduction for devices with 85K LE and 110K LE.





Resource		Member Code					
		C2	C4	C5	C6		
HPS PLL		3	3	3	3		
3 Gbps Transceiver		6	6	9	9		
FPGA GPIO (8)	FPGA GPIO (8)		145	288	288		
HPS I/O	HPS I/O		181	181	181		
LVDS	Transmitter	32	32	72	72		
	Receiver	37	37	72	72		
PCIe Hard IP Block		2	2	2 (9)	2 (9)		
FPGA Hard Memory	FPGA Hard Memory Controller		1	1	1		
HPS Hard Memory Controller		1	1	1	1		
Arm Cortex-A9 MP0	Core Processor	Dual-core	Dual-core	Dual-core	Dual-core		

### **Related Information**

True LVDS Buffers in Devices, I/O Features in Cyclone V Devices

Provides the number of LVDS channels in each device package.

### **Package Plan**

**Table 13.** Package Plan for Cyclone V SX Devices

The HPS I/O counts are the number of I/Os in the HPS and does not correlate with the number of HPS-specific I/O pins in the FPGA. Each HPS-specific pin in the FPGA may be mapped to several HPS I/Os.

Member Code	U672 (23 mm)			F896 (31 mm)		
	FPGA GPIO	HPS I/O	XCVR	FPGA GPIO	HPS I/O	XCVR
C2	145	181	6	_	_	_
C4	145	181	6	_	_	_
C5	145	181	6	288	181	9
C6	145	181	6	288	181	9

## **Cyclone V ST**

This section provides the available options, maximum resource counts, and package plan for the Cyclone V ST devices.

The information in this section is correct at the time of publication. For the latest information and to get more details, refer to the *Product Selector Guide*.

<sup>(8)</sup> The number of GPIOs does not include transceiver I/Os. In the Intel Quartus Prime software, the number of user I/Os includes transceiver I/Os.

<sup>(9) 1</sup> PCIe Hard IP Block in U672 package.



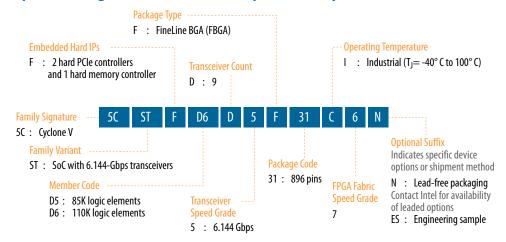
#### **Related Information**

#### **Product Selector Guide**

Provides the latest information about Intel products.

## **Available Options**

Figure 6. Sample Ordering Code and Available Options for Cyclone V ST Devices



### **Maximum Resources**

**Table 14.** Maximum Resource Counts for Cyclone V ST Devices

Reso	ource	Membe	r Code				
		D5	D6				
Logic Elements (LE) (K)		85	110				
ALM		32,070	41,910				
Register		128,300	166,036				
Memory (Kb)	M10K	3,970	5,570				
	MLAB	480	621				
Variable-precision DSP Block		87	112				
18 x 18 Multiplier		174	224				
FPGA PLL		6	6				
HPS PLL		3	3				
6.144 Gbps Transceiver		9	9				
FPGA GPIO <sup>(10)</sup>		288	288				
HPS I/O		181	181				
LVDS	LVDS Transmitter		72				

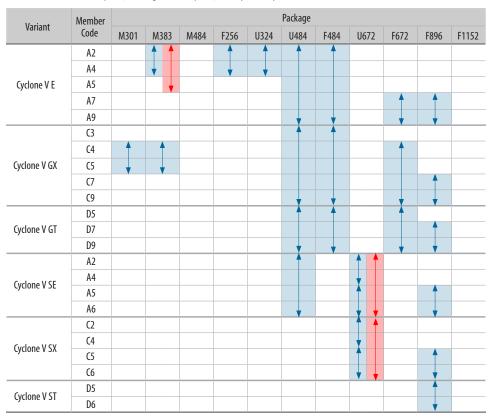
<sup>(10)</sup> The number of GPIOs does not include transceiver I/Os. In the Intel Quartus Prime software, the number of user I/Os includes transceiver I/Os.



## I/O Vertical Migration for Cyclone V Devices

### Figure 7. Vertical Migration Capability Across Cyclone V Device Packages and Densities

The arrows indicate the vertical migration paths. The devices included in each vertical migration path are shaded. You can also migrate your design across device densities in the same package option if the devices have the same dedicated pins, configuration pins, and power pins.



You can achieve the vertical migration shaded in red if you use only up to 175 GPIOs for the M383 package, and 138 GPIOs for the U672 package. These migration paths are not shown in the Intel Quartus Prime software Pin Migration View.

Note:

To verify the pin migration compatibility, use the Pin Migration View window in the Intel Quartus Prime software Pin Planner.

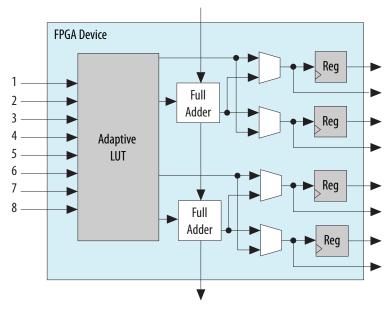
# **Adaptive Logic Module**

Cyclone V devices use a 28 nm ALM as the basic building block of the logic fabric.

The ALM, as shown in following figure, uses an 8-input fracturable look-up table (LUT) with four dedicated registers to help improve timing closure in register-rich designs and achieve an even higher design packing capability than previous generations.



Figure 8. ALM for Cyclone V Devices



You can configure up to 25% of the ALMs in the Cyclone V devices as distributed memory using MLABs.

#### **Related Information**

Embedded Memory Capacity in Cyclone V Devices on page 21 Lists the embedded memory capacity for each device.

## **Variable-Precision DSP Block**

Cyclone V devices feature a variable-precision DSP block that supports these features:

- Configurable to support signal processing precisions ranging from 9 x 9, 18 x 18 and 27 x 27 bits natively
- A 64-bit accumulator
- A hard preadder that is available in both 18- and 27-bit modes
- Cascaded output adders for efficient systolic finite impulse response (FIR) filters
- Internal coefficient register banks, 8 deep, for each multiplier in 18- or 27-bit mode
- Fully independent multiplier operation
- A second accumulator feedback register to accommodate complex multiplyaccumulate functions
- Fully independent Efficient support for single-precision floating point arithmetic
- The inferability of all modes by the Intel Quartus Prime design software



Variant	Member Code	Variable- precision DSP Block		dent Input and plications Ope	18 x 18 Multiplier Adder Mode	18 x 18 Multiplier	
		DSP Block	9 x 9 Multiplier	18 x 18 Multiplier	27 x 27 Multiplier	Adder Mode	Adder Summed with 36 bit Input
	C6	112	336	224	112	112	112
Cyclone V ST	D5	87	261	174	87	87	87
	D6	112	336	224	112	112	112

## **Embedded Memory Blocks**

The embedded memory blocks in the devices are flexible and designed to provide an optimal amount of small- and large-sized memory arrays to fit your design requirements.

## **Types of Embedded Memory**

The Cyclone V devices contain two types of memory blocks:

- 10 Kb M10K blocks—blocks of dedicated memory resources. The M10K blocks are ideal for larger memory arrays while still providing a large number of independent ports.
- 640 bit memory logic array blocks (MLABs)—enhanced memory blocks that are configured from dual-purpose logic array blocks (LABs). The MLABs are ideal for wide and shallow memory arrays. The MLABs are optimized for implementation of shift registers for digital signal processing (DSP) applications, wide shallow FIFO buffers, and filter delay lines. Each MLAB is made up of ten adaptive logic modules (ALMs). In the Cyclone V devices, you can configure these ALMs as ten 32 x 2 blocks, giving you one 32 x 20 simple dual-port SRAM block per MLAB.

## **Embedded Memory Capacity in Cyclone V Devices**

Table 18. Embedded Memory Capacity and Distribution in Cyclone V Devices

	Member	M1	ОК	ML	Total RAM Bit	
Variant	Code	Block	RAM Bit (Kb)	Block	RAM Bit (Kb)	(Kb)
Cyclone V E	A2	176	1,760	314	196	1,956
	A4	308	3,080	485	303	3,383
	A5	446	4,460	679	424	4,884
	A7	686	6,860	1338	836	7,696
	A9	1,220	12,200	2748	1,717	13,917
Cyclone V GX	C3	135	1,350	291	182	1,532
	C4	250	2,500	678	424	2,924
	C5	446	4,460	678	424	4,884
	C7	686	6,860	1338	836	7,696
	C9	1,220	12,200	2748	1,717	13,917
						continued



	Member	M1	.0К	ML	Total RAM Bit	
Variant	Code	Block	RAM Bit (Kb)	Block	RAM Bit (Kb)	(Kb)
Cyclone V GT	D5	446	4,460	679	424	4,884
	D7	686	6,860	1338	836	7,696
	D9	1,220	12,200	2748	1,717	13,917
Cyclone V SE	A2	140	1,400	221	138	1,538
	A4	270	2,700	370	231	2,460
	A5	397	3,970	768	480	4,450
	A6	553	5,530	994	621	6,151
Cyclone V SX	C2	140	1,400	221	138	1,538
	C4	270	2,700	370	231	2,460
	C5	397	3,970	768	480	4,450
	C6	553	5,530	994	621	6,151
Cyclone V ST	D5	397	3,970	768	480	4,450
	D6	553	5,530	994	621	6,151

## **Embedded Memory Configurations**

#### Table 19. Supported Embedded Memory Block Configurations for Cyclone V Devices

This table lists the maximum configurations supported for the embedded memory blocks. The information is applicable only to the single-port RAM and ROM modes.

Memory Block	Depth (bits)	Programmable Width
MLAB	32	x16, x18, or x20
M10K	256	x40 or x32
	512	x20 or x16
	1K	x10 or x8
	2K	x5 or x4
	4K	x2
	8K	x1

## **Clock Networks and PLL Clock Sources**

550 MHz Cyclone V devices have 16 global clock networks capable of up to operation. The clock network architecture is based on Intel's global, quadrant, and peripheral clock structure. This clock structure is supported by dedicated clock input pins and fractional PLLs.

Note:

To reduce power consumption, the Intel Quartus Prime software identifies all unused sections of the clock network and powers them down.



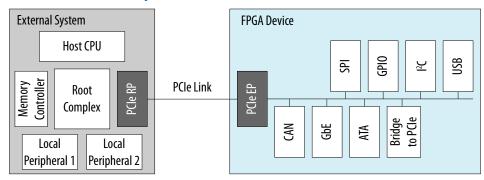
### PCIe Gen1 and Gen2 Hard IP

Cyclone V GX, GT, SX, and ST devices contain PCIe hard IP that is designed for performance and ease-of-use. The PCIe hard IP consists of the MAC, data link, and transaction layers.

The PCIe hard IP supports PCIe Gen2 and Gen1 end point and root port for up to x4 lane configuration. The PCIe Gen2 x4 support is PCIe-compatible.

The PCIe endpoint support includes multifunction support for up to eight functions, as shown in the following figure. The integrated multifunction support reduces the FPGA logic requirements by up to 20,000 LEs for PCIe designs that require multiple peripherals.

Figure 9. PCIe Multifunction for Cyclone V Devices



The Cyclone V PCIe hard IP operates independently from the core logic. This independent operation allows the PCIe link to wake up and complete link training in less than 100 ms while the Cyclone V device completes loading the programming file for the rest of the device.

In addition, the PCIe hard IP in the Cyclone V device provides improved end-to-end datapath protection using ECC.

## **External Memory Interface**

This section provides an overview of the external memory interface in Cyclone V devices.

## **Hard and Soft Memory Controllers**

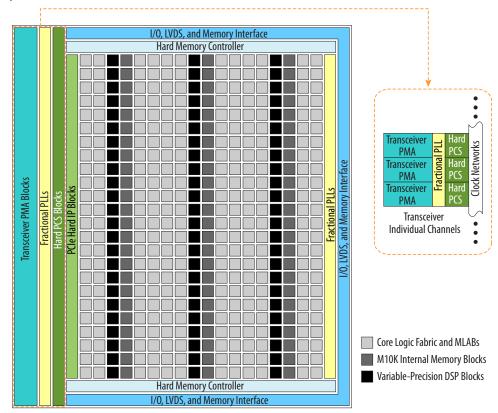
Cyclone V devices support up to two hard memory controllers for DDR3, DDR2, and LPDDR2 SDRAM devices. Each controller supports 8 to 32 bit components of up to 4 gigabits (Gb) in density with two chip selects and optional ECC. For the Cyclone V SoC devices, an additional hard memory controller in the HPS supports DDR3, DDR2, and LPDDR2 SDRAM devices.

All Cyclone V devices support soft memory controllers for DDR3, DDR2, and LPDDR2 SDRAM devices for maximum flexibility.



Figure 10. Device Chip Overview for Cyclone V GX and GT Devices

The figure shows a Cyclone V FPGA with transceivers. Different Cyclone V devices may have a different floorplans than the one shown here.



### **PMA Features**

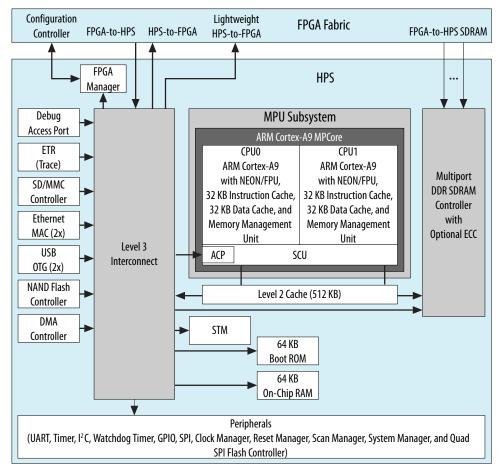
To prevent core and I/O noise from coupling into the transceivers, the PMA block is isolated from the rest of the chip—ensuring optimal signal integrity. For the transceivers, you can use the channel PLL of an unused receiver PMA as an additional transmit PLL.

Table 22. PMA Features of the Transceivers in Cyclone V Devices

Features	Capability
Backplane support	Driving capability up to 6.144 Gbps
PLL-based clock recovery	Superior jitter tolerance
Programmable deserialization and word alignment	Flexible deserialization width and configurable word alignment pattern
Equalization and pre-emphasis	<ul> <li>Up to 14.37 dB of pre-emphasis and up to 4.7 dB of equalization</li> <li>No decision feedback equalizer (DFE)</li> </ul>
Ring oscillator transmit PLLs	614 Mbps to 6.144 Gbps
Input reference clock range	20 MHz to 400 MHz
Transceiver dynamic reconfiguration	Allows the reconfiguration of a single channel without affecting the operation of other channels



Figure 11. HPS with Dual-Core Arm Cortex-A9 MPCore Processor



### **System Peripherals and Debug Access Port**

Each Ethernet MAC, USB OTG, NAND flash controller, and SD/MMC controller module has an integrated DMA controller. For modules without an integrated DMA controller, an additional DMA controller module provides up to eight channels of high-bandwidth data transfers. Peripherals that communicate off-chip are multiplexed with other peripherals at the HPS pin level. This allows you to choose which peripherals to interface with other devices on your PCB.

The debug access port provides interfaces to industry standard JTAG debug probes and supports Arm CoreSight debug and core traces to facilitate software development.

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Note:

Although the FPGA fabric and HPS are on separate power domains, the HPS must remain powered up during operation while the FPGA fabric can be powered up or down as required.

#### **Related Information**

Cyclone V Device Family Pin Connection Guidelines

Provides detailed information about power supply pin connection guidelines and power regulator sharing.

## **Hardware and Software Development**

For hardware development, you can configure the HPS and connect your soft logic in the FPGA fabric to the HPS interfaces using the Platform Designer (Standard) system integration tool in the Intel Quartus Prime software.

For software development, the Arm-based SoC devices inherit the rich software development ecosystem available for the Arm Cortex-A9 MPCore processor. The software development process for Intel SoCs follows the same steps as those for other SoC devices from other manufacturers. Support for Linux, VxWorks<sup>®</sup>, and other operating systems is available for the SoCs. For more information on the operating systems support availability, contact the Intel sales team.

You can begin device-specific firmware and software development on the Intel SoC Virtual Target. The Virtual Target is a fast PC-based functional simulation of a target development system—a model of a complete development board that runs on a PC. The Virtual Target enables the development of device-specific production software that can run unmodified on actual hardware.

#### **Related Information**

International Altera Sales Support Offices

## **Dynamic and Partial Reconfiguration**

The Cyclone V devices support dynamic reconfiguration and partial reconfiguration.

### **Dynamic Reconfiguration**

The dynamic reconfiguration feature allows you to dynamically change the transceiver data rates, PMA settings, or protocols of a channel, without affecting data transfer on adjacent channels. This feature is ideal for applications that require on-the-fly multiprotocol or multirate support. You can reconfigure the PMA and PCS blocks with dynamic reconfiguration.

## **Partial Reconfiguration**

Note:

The partial reconfiguration feature is available for Cyclone V E, GX, SE, and SX devices with the "SC" suffix in the part number. For device availability and ordering, contact your local Intel sales representatives.

Partial reconfiguration allows you to reconfigure part of the device while other sections of the device remain operational. This capability is important in systems with critical uptime requirements because it allows you to make updates or adjust functionality without disrupting services.



## **Power Management**

Leveraging the FPGA architectural features, process technology advancements, and transceivers that are designed for power efficiency, the Cyclone V devices consume less power than previous generation Cyclone FPGAs:

- Total device core power consumption—less by up to 40%.
- Transceiver channel power consumption—less by up to 50%.

Additionally, Cyclone V devices contain several hard IP blocks that reduce logic resources and deliver substantial power savings of up to 25% less power than equivalent soft implementations.

# **Document Revision History for Cyclone V Device Overview**

Document Version	Changes
2018.05.07	<ul> <li>Added the low power option ("L" suffix) for Cyclone V SE and Cyclone V SX devices in the Sample Ordering Code and Available Options diagrams.</li> <li>Rebranded as Intel.</li> </ul>

Date	Version	Changes
December 2017	2017.12.18	Updated ALM resources for Cyclone V E, Cyclone V SE, Cyclone V SX, and Cyclone V ST devices.
June 2016	2016.06.10	Updated Cyclone V GT speed grade to -7 in Sample Ordering Code and Available Options for Cyclone V GT Devices diagram.
December 2015	2015.12.21	<ul> <li>Added descriptions to package plan tables for Cyclone V GT and ST devices.</li> <li>Changed instances of <i>Quartus II</i> to <i>Quartus Prime</i>.</li> </ul>
June 2015	2015.06.12	<ul> <li>Replaced a note to partial reconfiguration feature. Note: The partial reconfiguration feature is available for Cyclone V E, GX, SE, and SX devices with the "SC" suffix in the part number. For device availability and ordering, contact your local Altera sales representatives.</li> <li>Updated logic elements (LE) (K) for the following devices:         <ul> <li>Cyclone V E A7: Updated from 149.5 to 150</li> <li>Cyclone V GX C3: Updated from 35.5 to 36</li> <li>Cyclone V GX C7: Updated from 149.7 to 150</li> <li>Cyclone V GT D7: Updated from 149.5 to 150</li> </ul> </li> <li>Updated MLAB (Kb) in Maximum Resource Counts for Cyclone V GX Devices table as follows:         <ul> <li>Cyclone V GX C3: Updated from 291 to 182</li> <li>Cyclone V GX C4: Updated from 678 to 424</li> <li>Cyclone V GX C5: Updated from 1,338 to 836</li> <li>Cyclone V GX C9: Updated from 2,748 to 1,717</li> </ul> </li> </ul>
		continued



Date	Version	Changes
July 2014	2014.07.07	Updated the I/O vertical migration figure to clarify the migration capability of Cyclone V SE and SX devices.
December 2013	2013.12.26	<ul> <li>Cyclone V SE and SX devices.</li> <li>Corrected single or dual-core ARM Cortex-A9 MPCore processor-up to 925 MHz from 800 MHz.</li> <li>Removed "Preliminary" texts from Ordering Code figures, Maximum Resources, Package Plan and I/O Vertical Migration tables.</li> <li>Removed the note "The number of GPIOs does not include transceiver I/Os. In the Quartus II software, the number of user I/Os includes transceiver I/Os." for GPIOs in the Maximum Resource Counts table for Cyclone V E and SE.</li> <li>Added link to Altera Product Selector for each device variant.</li> <li>Updated Embedded Hard IPs for Cyclone V GT devices to indicate Maximum 2 hard PCIe and 2 hard memory controllers.</li> <li>Added leaded package options.</li> <li>Removed the note "The number of PLLs includes general-purpose fractional PLLs and transceiver fractional PLLs." for all PLLs in the Maximum Resource Counts table.</li> <li>Corrected max LVDS counts for transmitter and receiver for Cyclone V E A5 device from 84 to 60.</li> <li>Corrected max LVDS counts for transmitter and receiver for Cyclone V E A9 device from 140 to 120.</li> <li>Corrected variable-precision DSP block, 27 x 27 multiplier, 18 x 18 multiplier adder mode and 18 x 18 multiplier adder summed with 36 bit input for Cyclone V SE devices from 58 to 84.</li> <li>Corrected 18 x 18 multiplier for Cyclone V SE devices from 174 to 252.</li> <li>Corrected LVDS transmitter for Cyclone V SE A2 and A4 as well as SX C2 and C4 devices from 31 to 32.</li> <li>Corrected LVDS receiver for Cyclone V SE A2 and A4 as well as SX C2 and C4 devices from 35 to 37.</li> <li>Corrected transceiver speed grade for Cyclone V ST devices ordering code from 4 to 5.</li> <li>Updated the DDR3 SDRAM for the maximum frequency's soft controller and the minimum frequency from 300 to 303 for voltage 1.35v.</li> <li>Added links to Altera's External Memory Spec Estimator tool to the topics</li> </ul>
		<ul> <li>listing the external memory interface performance.</li> <li>Corrected XAUI is supported through the soft PCS in the PCS features for Cyclone V.</li> <li>Added decompression support for the CvP configuration mode.</li> </ul>
		Added decompression support for the CVF configuration mode.
May 2013	2013.05.06	<ul> <li>Added link to the known document issues in the Knowledge Base.</li> <li>Moved all links to the Related Information section of respective topics for easy reference.</li> </ul>
		<ul> <li>Corrected the title to the PCIe hard IP topic. Cyclone V devices support only PCIe Gen1 and Gen2.</li> <li>Updated Supporting Feature in Table 1 of Increased bandwidth capacity to</li> </ul>
		'6.144 Gbps'.  • Updated Description in Table 2 of Low-power high-speed serial interface to
		'6.144 Gbps'.
		<ul> <li>Updated Description in Table 3 of Cyclone V GT to '6.144 Gbps'.</li> <li>Updated the M386 package to M383 for Figure 1, Figure 2 and Figure 3.</li> </ul>
		<ul> <li>Updated Figure 2 and Figure 3 for Transceiver Count by adding 'F : 4'.</li> </ul>
		<ul> <li>Updated LVDS in the Maximum Resource Counts tables to include Transmitter and Receiver values.</li> </ul>
		Updated the package plan with M383 for the Cyclone V E device.
		<ul> <li>Removed the M301 and M383 packages from the Cyclone V GX C4 device.</li> <li>Updated the GPIO count to '129' for the M301 package of the Cyclone V GX C5 device.</li> </ul>
		Updated 5 Gbps to '6.144 Gbps' forCyclone V GT device.
	<b>'</b>	continued



Date	Version	Changes
		<ul> <li>Updated HPS I/O for U484 (19 mm) in Table 11 with '151' for A2, A4, A5 and A6.</li> <li>Updated Memory (Kb) for Maximum Resource Counts for Cyclone V SE A4 and A6, SX C4 and C6, ST D6 devices.</li> <li>Updated FPGA PLL for Maximum Resource Counts for Cyclone V SE A2, SX C2, devices.</li> <li>Removed '36 x 36' from the Variable-Precision DSP Block.</li> <li>Updated Variable-precision DSP Blocks and 18 x 18 Multiplier for Maximum Resource Counts for Cyclone V SX C4 device.</li> <li>Updated the HPS I/O counts for Cyclone V SE, SX, and ST devices.</li> <li>Updated Figure 7 which shows the I/O vertical migration table.</li> <li>Updated Table 17 for Cyclone V SX C4 device.</li> <li>Updated Embedded Memory Capacity and Distribution table for Cyclone V SE A4 and A6, SX C4 and C6, ST D6 devices.</li> <li>Removed 'Counter reconfiguration' from the PLL Features.</li> <li>Updated Low-Power Serial Transceivers by replacing 5 Gbps with 6.144 Gbps.</li> <li>Removed 'Distributed Memory' symbol.</li> <li>Updated the Capability in Table 22 of Backplane support to '6.144 Gbps'.</li> <li>Updated Capability in Table 22 of Ring oscillator transmit PLLs with 6.144 Gbps.</li> <li>Updated the PCS Support in Table 23 from 5 Gbps to '6 Gbps'.</li> <li>Updated the Data Rates (Gbps) in Table 23 of CPRI 4.1 to '6.144 Gbps'.</li> <li>Updated the Data Rates (Gbps) in Table 23 of CPRI 4.1 to '6.144 Gbps'.</li> <li>Clarified that partial reconfiguration is an advanced feature. Contact Altera for support of the feature.</li> </ul>
December 2012	2012.12.28	<ul> <li>Updated the pin counts for the MBGA packages.</li> <li>Updated the GPIO and transceiver counts for the MBGA packages.</li> <li>Updated the GPIO counts for the U484 package of the Cyclone V E A9, GX C9, and GT D9 devices.</li> <li>Updated the vertical migration table for vertical migration of the U484 packages.</li> <li>Updated the MLAB supported programmable widths at 32 bits depth.</li> </ul>
November 2012	2012.11.19	<ul> <li>Added new MBGA packages and additional U484 packages for Cyclone V E, GX, and GT.</li> <li>Added ordering code for five-transceiver devices for Cyclone V GT and ST.</li> <li>Updated the vertical migration table to add MBGA packages.</li> <li>Added performance information for HPS memory controller.</li> <li>Removed DDR3U support.</li> <li>Updated Cyclone V ST speed grade information.</li> <li>Added information on maximum transceiver channel usage restrictions for PCI Gen2 and CPRI at 4.9152 Gbps transmit jitter compliance.</li> <li>Added note on the differences between GPIO reported in Overview with User I/O numbers shown in the Quartus II software.</li> <li>Updated template.</li> </ul>
July 2012	2.1	Added support for PCIe Gen2 x4 lane configuration (PCIe-compatible)
June 2012	2.0	<ul> <li>Restructured the document.</li> <li>Added the "Embedded Memory Capacity" and "Embedded Memory Configurations" sections.</li> <li>Added Table 1, Table 3, Table 16, Table 19, and Table 20.</li> <li>Updated Table 2, Table 4, Table 5, Table 6, Table 7, Table 8, Table 9, Table 10, Table 11, Table 12, Table 13, Table 14, Table 17, and Table 18.</li> </ul>

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Date	Version	Changes
		<ul> <li>Updated Figure 1, Figure 2, Figure 3, Figure 4, Figure 5, Figure 6, and Figure 10.</li> <li>Updated the "FPGA Configuration and Processor Booting" and "Hardware and Software Development" sections.</li> <li>Text edits throughout the document.</li> </ul>
February 2012	1.2	<ul> <li>Updated Table 1-2, Table 1-3, and Table 1-6.</li> <li>Updated "Cyclone V Family Plan" on page 1-4 and "Clock Networks and PLL Clock Sources" on page 1-15.</li> <li>Updated Figure 1-1 and Figure 1-6.</li> </ul>
November 2011	1.1	<ul> <li>Updated Table 1-1, Table 1-2, Table 1-3, Table 1-4, Table 1-5, and Table 1-6.</li> <li>Updated Figure 1-4, Figure 1-5, Figure 1-6, Figure 1-7, and Figure 1-8.</li> <li>Updated "System Peripherals" on page 1-18, "HPS-FPGA AXI Bridges" on page 1-19, "HPS SDRAM Controller Subsystem" on page 1-19, "FPGA Configuration and Processor Booting" on page 1-19, and "Hardware and Software Development" on page 1-20.</li> <li>Minor text edits.</li> </ul>
October 2011	1.0	Initial release.